NOTES: unless otherwise specified

1.0 Fabricate circuit board to conform to IPC-A-600B

2.0 BASE MATERIAL
2.1 Laminate base material shall be natural color, FR370 or equivalent.

3.0 COPPER PLATING
3.1 Copper plating shall have a minimum purity of 99.5 percent and a minimum thickness of .001 inch. This also applies to the plating in the holes.

4.0 SOLDERMASK
4.1 Apply LPI Green soldermask over bare copper according to the soldermask pattern file per IPC-SM-840B.

5.0 FINISH
5.1 Exposed copper shall be Ni/Au — Immersion Gold 3–5u INCH (0.000003–0.000058) OVER ELECTROLESS NICKEL 100–200u INCH (0.00001–0.000008) THICK LAM IPC-2221 AND IPC-4552 (ENG).

6.0 SILK SCREEN
6.1 Silk screen top (+1) and bottom (+4) side of board using white epoxy ink according to the –15 pattern film and the –45 pattern film. Ink shall not cover any exposed metal.

7.0 DIMENSIONS
7.1 All dimensions are in inches.
7.2 Unless otherwise specified all hole sizes apply after plating.

8.0 TOLERANCES
8.1 Hole size tolerance ± .003 after plating unless otherwise specified.

9.0 APPEARANCE
9.1 All inside and outside corners shall have a maximum radius of .005
9.2 Remove all burrs and smooth sharp edges to .010 max.

VENDOR NOTE: NOTIFY US OF ANY CONFLICTING REQUIREMENTS OR IF BOARDS CANNOT BE MANUFACTURERED TO MEET THE ABOVE REQUIREMENTS, DUE TO VENDORS PROCESS AND/OR SPECIFICATIONS OR BECAUSE PHOTO TOOLS AND/OR SPECIFICATIONS ARE INADEQUATE.

Array of 4 on a tabbed panel
Space between boards on long edge should be a minimum of .6 inches

Modified Date: Fri Mar 18, 2011
Print Date: Fri Mar 18, 2011